TAIWAN SEMICONDUCTOR

Product/ Process Change Notification

1. PCN No.:	**QPCN12005**
2. Subject:	GBL/GBU/TS4B/TS6P package bridge rectifiers, upgrades from manual die soldering to auto die attached in soldering process
3. To:	Only to Asia all territories
4. Issued by:	Owen Wang
5. Issue date:	21st Mar, '12
6. Proposed first ship date for change:	26th Jun, '12

7. Affected Product Identification

Please see Appendix A – by package type.

***8.* Change Description : (OLD Vs. NEW Comparison)**

Old:

Manual soldering and Auto. die attached in soldering process are parallel production.

	Compound	Manual
Non-forming	Non-green	C2
	Green	C2G
Forming	Non-green	X0
	Green	X0G

New:

Only production is for Auto. die attached in soldering process.

	Compound	Auto.
Non-forming	Non-green	C2
	Green	C2G
Forming	Non-green	X0
	Green	X0G

9. Reason for Change:

To increase production capacity and automation we upgrade to automated die attached lines. Automated die attached line product has been qualified (in accordance with AEC-Q101-REV-C) at YEW plant.

10. Anticipated Impact: (form, fit, function, quality or reliability)

1. Product outline: No change
2. Inner construction changed: (Please see Appendix B – Construction diagrams)
3. Electrical specifications: No change
4. Reliability/performance: No change
5. Data sheet: No change
6. Packing code (order code): No change

***11.* Qualification plan/result:**

12. Sample availability Date:	21st Mar, '12
13. Tentative implementation date:	21st Mar, '12

14. Remarks

15. Customer feedback required latest: (should we receive no feedback; the change will be deemed as accepted!)	**26th Apr, '12**
16. Approved by:	Quayer Chen

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Customer Approval Form_QPCN12005

(Please tick the field what is valid for you!)

☐ **We agree with this proposed change and its schedule.**	
☐ **We have objections**	
☐ **We need more information:**	
☐ **We need sample:**	
Company:	
Name:	
Address:	
Signature:	**Date:**

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Appendix

A (Affected product Identification): by package type

GBL 2A		GBL 4A		GBU 4A	GBU 6A
D2SB05	GBL201	GBLA005	GBL005	GBU401	GBU601
D2SB10	GBL202	GBLA01	GBL01	GBU402	GBU602
D2SB20	GBL203	GBLA02	GBL02	GBU403	GBU603
D2SB40	GBL204	GBLA04	GBL04	GBU404	GBU604
D2SB60	GBL205	GBLA06	GBL06	GBU405	GBU605
D2SB80	GBL206	GBLA08	GBL08	GBU406	GBU606
	GBL207	GBLA10	GBL10	GBU407	GBU607
GBU 8A	GBU 10A	TS4B 4A	TS4B 6A	TS4B 10A	TS6P 6A
GBU801	GBU1001	TS4B01G	TS6B01G	TS10B01G	TS6P01G
GBU802	GBU1002	TS4B02G	TS6B02G	TS10B02G	TS6P02G
GBU803	GBU1003	TS4B03G	TS6B03G	TS10B03G	TS6P03G
GBU804	GBU1004	TS4B04G	TS6B04G	TS10B04G	TS6P04G
GBU805	GBU1005	TS4B05G	TS6B05G	TS10B05G	TS6P05G
GBU806	GBU1006	TS4B06G	TS6B06G	TS10B06G	TS6P06G
GBU807	GBU1007	TS4B07G	TS6B07G	TS10B07G	TS6P07G
TS6P 8A	TS6P 10A	TS6P 15A	TS6P 20A	TS6P 25A	
TS8P01G	TS10P01G	TS15P01G	TS20P01G	TS25P01G	
TS8P02G	TS10P02G	TS15P02G	TS20P02G	TS25P02G	
TS8P03G	TS10P03G	TS15P03G	TS20P03G	TS25P03G	
TS8P04G	TS10P04G	TS15P04G	TS20P04G	TS25P04G	
TS8P05G	TS10P05G	TS15P05G	TS20P05G	TS25P05G	
TS8P06G	TS10P06G	TS15P06G	TS20P06G	TS25P06G	
TS8P07G	TS10P07G	TS15P07G	TS20P07G	TS25P07G	

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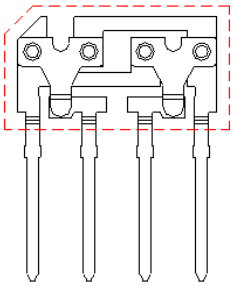
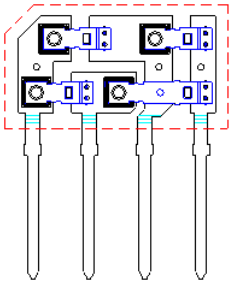
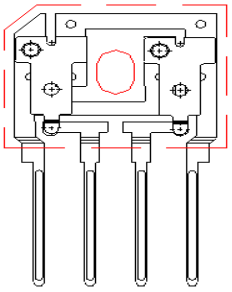
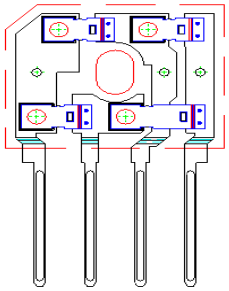
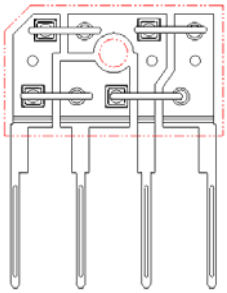
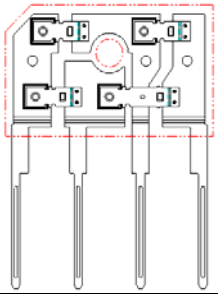
Appendix

B (Anticipated Impact): by construction diagrams

	Old	New
GBL		
GBU		
TS4B		
TS6P